



Material Content Data Sheet



Halogen-Free

Sales Product Name	AIKB50N65DH5	Issued	12. May 2021
MA#	MA001835662		
Package	PG-TO263-3-2	Weight*	1562.47 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	1.008	0.06	0.06	645	645
chip_2	inorganic material	silicon	7440-21-3	2.728	0.17	0.17	1746	1746
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		195	
	non noble metal	copper	7440-50-8	304.026	19.46	19.49	194581	194834
wire	non noble metal	aluminium	7429-90-5	10.772	0.69	0.69	6894	6894
encapsulation	inorganic material	zinc oxide	1314-13-2	6.808	0.44		4357	
	miscellaneous	miscellaneous	-	27.233	1.74		17429	
	plastics	epoxy resin	-	102.122	6.54		65360	
	inorganic material	silicon dioxide	60676-86-0	544.653	34.86	43.58	348586	435732
lead finish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6180	6180
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.089	0.01		57	
	noble metal	silver	7440-22-4	0.111	0.01		71	
	non noble metal	lead	7439-92-1	4.256	0.27	0.29	2724	2852
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		351	
	non noble metal	copper	7440-50-8	547.666	35.04	35.09	350514	350970
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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